

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT6207694

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SAI SRIKANTH GOLAGANI VENKATA KANAKA	05/14/2020
ZHEN YUN LIU	05/11/2020
RECEIVING PARTY DATA	
Name:	HERAEUS MATERIALS SINGAPORE PTE. LTD.
Street Address:	BLOCK 5014, ANG MO KIO AVENUE 5
Internal Address:	#07-01 TECHPLACE II
City:	SINGAPORE
State/Country:	SINGAPORE
Postal Code:	569881
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16749495
CORRESPONDENCE DATA	
Fax Number:	(612)573-2005
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	(612) 573-2000
Email:	USPTO.PATENTS@dbclaw.com
Correspondent Name:	DICKE, BILLIG & CZAJA, PLLC
Address Line 1:	100 SOUTH FIFTH STREET
Address Line 2:	SUITE 2250
Address Line 4:	MINNEAPOLIS, MINNESOTA 55402
ATTORNEY DOCKET NUMBER:	M688.107.101
NAME OF SUBMITTER:	PAUL P. KEMPF
SIGNATURE:	/paulpkempf/
DATE SIGNED:	07/20/2020
Total Attachments: 6	
source=2020-07-16-DecAssignGVK#page1.tif	
source=2020-07-16-DecAssignGVK#page2.tif	
source=2020-07-16-DecAssignGVK#page3.tif	

source=2020-07-16-DecAssignLIU#page1.tif

source=2020-07-16-DecAssignLIU#page2.tif

source=2020-07-16-DecAssignLIU#page3.tif

PATENT

REEL: 053250 FRAME: 0140

ASSIGNMENT AND DECLARATION

WHEREAS, we:

<u>Inventor</u>	<u>Citizenship</u>	<u>Address</u>
Sai Srikanth GOLAGANI VENKATA KANAKA	IN	Block 586, Woodlands Drive 16 730586 Singapore SINGAPORE

(hereinafter referred to as "ASSIGNORS"), have made a discovery or invention ("INVENTION") entitled:

METHOD FOR MANUFACTURING A BIOCOMPATIBLE WIRE

- ☐ for which an application for Letters Patent of the United States has been executed on even date herewith,
- ☒ for which an application for Letters Patent of the United States has been filed on January 22, 2020, bearing Serial No. 16/749,495.

ASSIGNMENT

WHEREAS, at the time the INVENTION was made, ASSIGNORS were under an obligation to assign all rights, title, and interest in ASSIGNORS' INVENTION to:

Heraeus Materials Singapore Pte. Ltd.
Block 5014, Ang Mo Kio Avenue 5,
#07-01 TechPlace II
SINGAPORE 569881
SINGAPORE

and its legal representatives, successors, and assigns (hereinafter referred to as "ASSIGNEES"), which desires to formalize the assignment and its ownership of the entire interest in, to and under said INVENTION and in, to and under any and all applications for patent thereon and all Letters Patent which may be granted thereon.

NOW, THEREFORE, for valuable consideration received by ASSIGNORS, receipt and sufficiency of which is hereby acknowledged and agreed, and intending to be legally bound hereby, ASSIGNORS have assigned and hereby assign to ASSIGNEES, the entire right, title and interest to said INVENTION in the United States and its territorial possessions and in all foreign countries and to all Letters Patent or similar legal protection in the United States and its territorial possessions and in any and all foreign countries to be obtained for said INVENTION by said applications or any patent applications related thereto, including, but not limited to, continuations, divisionals, reexaminations or reissues thereof or any legal equivalent thereof in the United States and all foreign countries for the full term or terms for which the same may be granted.

WE, SAID ASSIGNORS, hereby covenant that we have full right to convey the entire right, title and interest herein to ASSIGNEE;

WE, SAID ASSIGNORS, hereby authorize ASSIGNEES, or its representatives, to insert the filing date and serial number of the application when these are known;

AND WE, SAID ASSIGNORS, hereby further covenant and agree that the ASSIGNEES may apply for foreign Letters Patent on said INVENTION, and that we will, at any time, when called upon to do so by the ASSIGNEES communicate to the ASSIGNEES as the case may be, any facts known to us respecting said INVENTION, and execute and deliver any and all lawful papers that may be necessary or desirable to perfect the title to the said INVENTION, the said applications and the said Letters Patent in the ASSIGNEES and that if reissues of the said Letters Patent or disclaimers relating thereto, or continuations, divisionals, reexaminations, or reissues of the said applications, or any thereof, shall hereafter be desired by the ASSIGNEES, we will, at any time, when requested by ASSIGNEES, sign all lawful papers, make all rightful oaths, execute and deliver all such disclaimers and all continuations, divisionals, reexaminations, or reissues of said applications so desired, and generally do everything possible to aid ASSIGNEES to obtain and enforce proper patent protection for said INVENTION, and without further compensation, but at the expense of the ASSIGNEES.

DECLARATION

As an above-named inventor, I hereby declare that:

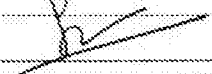
This declaration is directed to the United States application referenced above.

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention (or claimed design) in the above-identified application for which this declaration is being submitted.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

Signature: 	Date: 14-MAY-2020
Legal Name of Inventor: Sai Srikanth GOLAGANI VENKATA KANAKA	Citizenship: IN

ASSIGNMENT AND DECLARATION

WHEREAS, we:

<u>Inventor</u>	<u>Citizenship</u>	<u>Address</u>
Zhen Yun LIU	AU	Block 973, Hougang Street 91 Unit 14-214 530973 Singapore SINGAPORE

(hereinafter referred to as "ASSIGNORS"), have made a discovery or invention ("INVENTION") entitled:

METHOD FOR MANUFACTURING A BIOCOMPATIBLE WIRE

- ☐ for which an application for Letters Patent of the United States has been executed on even date herewith,
- ☒ for which an application for Letters Patent of the United States has been filed on January 22, 2020, bearing Serial No. 16/749,495.

ASSIGNMENT

WHEREAS, at the time the INVENTION was made, ASSIGNORS were under an obligation to assign all rights, title, and interest in ASSIGNORS' INVENTION to:

Heraeus Materials Singapore Pte. Ltd.
Block 5014, Ang Mo Kio Avenue 5,
#07-01 TechPlace II
SINGAPORE 569881
SINGAPORE

and its legal representatives, successors, and assigns (hereinafter referred to as "ASSIGNEES"), which desires to formalize the assignment and its ownership of the entire interest in, to and under said INVENTION and in, to and under any and all applications for patent thereon and all Letters Patent which may be granted thereon.

NOW, THEREFORE, for valuable consideration received by ASSIGNORS, receipt and sufficiency of which is hereby acknowledged and agreed, and intending to be legally bound hereby, ASSIGNORS have assigned and hereby assign to ASSIGNEES, the entire right, title and interest to said INVENTION in the United States and its territorial possessions and in all foreign countries and to all Letters Patent or similar legal protection in the United States and its territorial possessions and in any and all foreign countries to be obtained for said INVENTION by said applications or any patent applications related thereto, including, but not limited to, continuations, divisionals, reexaminations or reissues thereof or any legal equivalent thereof in the United States and all foreign countries for the full term or terms for which the same may be granted.

WE, SAID ASSIGNORS, hereby covenant that we have full right to convey the entire right, title and interest herein to ASSIGNEE;

WE, SAID ASSIGNORS, hereby authorize ASSIGNEES, or its representatives, to insert the filing date and serial number of the application when these are known;

AND WE, SAID ASSIGNORS, hereby further covenant and agree that the ASSIGNEES may apply for foreign Letters Patent on said INVENTION, and that we will, at any time, when called upon to do so by the ASSIGNEES communicate to the ASSIGNEES as the case may be, any facts known to us respecting said INVENTION, and execute and deliver any and all lawful papers that may be necessary or desirable to perfect the title to the said INVENTION, the said applications and the said Letters Patent in the ASSIGNEES and that if reissues of the said Letters Patent or disclaimers relating thereto, or continuations, divisionals, reexaminations, or reissues of the said applications, or any thereof, shall hereafter be desired by the ASSIGNEES, we will, at any time, when requested by ASSIGNEES, sign all lawful papers, make all rightful oaths, execute and deliver all such disclaimers and all continuations, divisionals, reexaminations, or reissues of said applications so desired, and generally do everything possible to aid ASSIGNEES to obtain and enforce proper patent protection for said INVENTION, and without further compensation, but at the expense of the ASSIGNEES.

DECLARATION

As an above-named inventor, I hereby declare that:

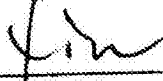
This declaration is directed to the United States application referenced above.

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention (or claimed design) in the above-identified application for which this declaration is being submitted.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

Signature: 	Date: <u>11-May-2020</u>
Legal Name of Inventor: Zhen Yun LIU	Citizenship: <u>AU</u>